

**AMENDMENTS TO THE CLAIMS**

1-17. (Canceled)

18. (Currently amended) An imaging device, comprising:

a die having a first surface containing an array of imaging elements; and

a transparent element adhesively attached to the die by an adhesive material ~~and having a first surface facing the first surface of the die~~, the first surface of the die having at least one adhesive flow restriction area for impeding flow of an adhesive across the first surface of the die, wherein the adhesive flow restriction area comprises at least one trench extending below the first surface of the die.

19. (Previously presented) The imaging device of claim 18, wherein the at least one trench has a curved shape.

20. (Previously presented) The imaging device of claim 18, wherein the at least one trench creates a perimeter around the array of imaging elements.

21. (Previously presented) The imaging device of claim 20, further comprising a second trench creating a perimeter around the at least one trench.

22. (Previously presented) The imaging device of claim 18, wherein the at least one trench extends from edge to edge of the die.

23-62. (Canceled)

63. (Previously presented) The imaging device of claim 18, wherein the transparent element is comprised of a material selected from the group consisting of glass, an optical thermoplastic material, a polyimide, a thermoset resin, a photosensitive gelatin, and a radiation curable resin.

64. (Previously presented) The imaging device of claim 18, wherein the adhesive material at an edge of the transparent element completely covers wire bonds electrically connecting the die to conductive lines.

65. (Previously presented) The imaging device of claim 18, wherein the die is associated with a substrate.

66. (Previously presented) The imaging device of claim 18, wherein the die is electrically connected to conductive tape by at least one conductive structure.

67. (Previously presented) The imaging device of claim 66, wherein the at least one conductive structure is a solder ball.

68. (Previously presented) The imaging device of claim 18, wherein the imaging element is comprised of an array of pixels, the pixels providing electrical signals corresponding to a response from light radiation.

69. (Previously presented) The imaging device of claim 18, wherein the imaging element is comprised of an array of pixels, the pixels capable of displaying an image corresponding to electrical signals.

70. (Previously presented) The imaging device of claim 18, wherein a vacant space between the transparent element and the array of imaging elements is hermetically sealed by the adhesive material.

71-78 (Cancelled).

79. (New) The imaging device of claim 21, wherein the second trench extends below the first surface of the die.